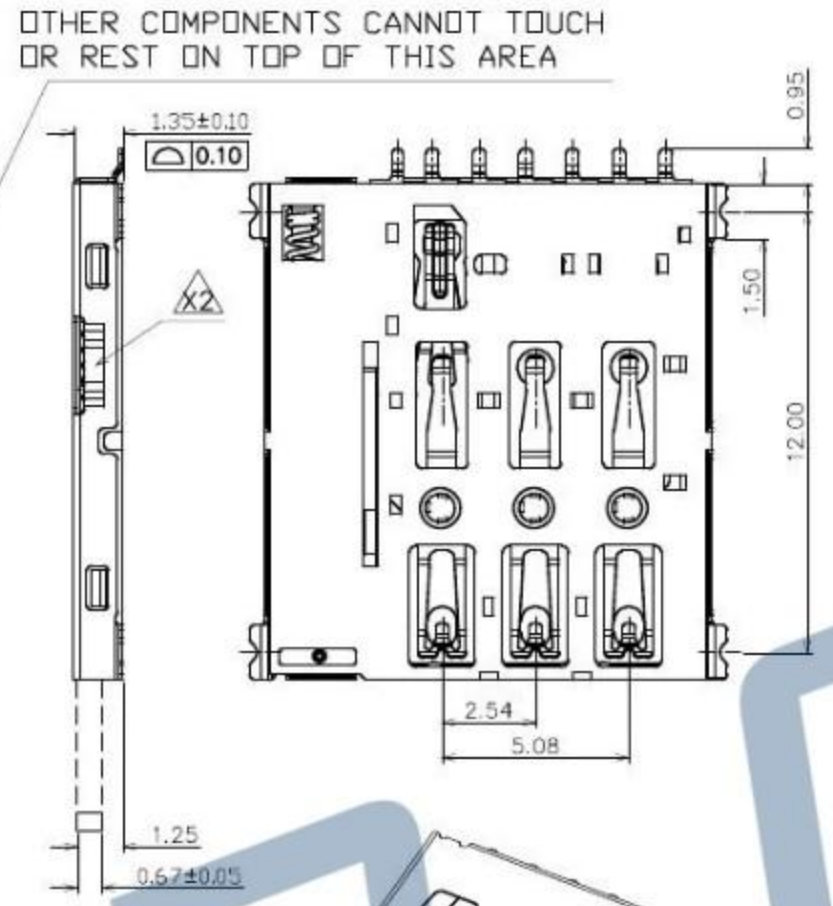
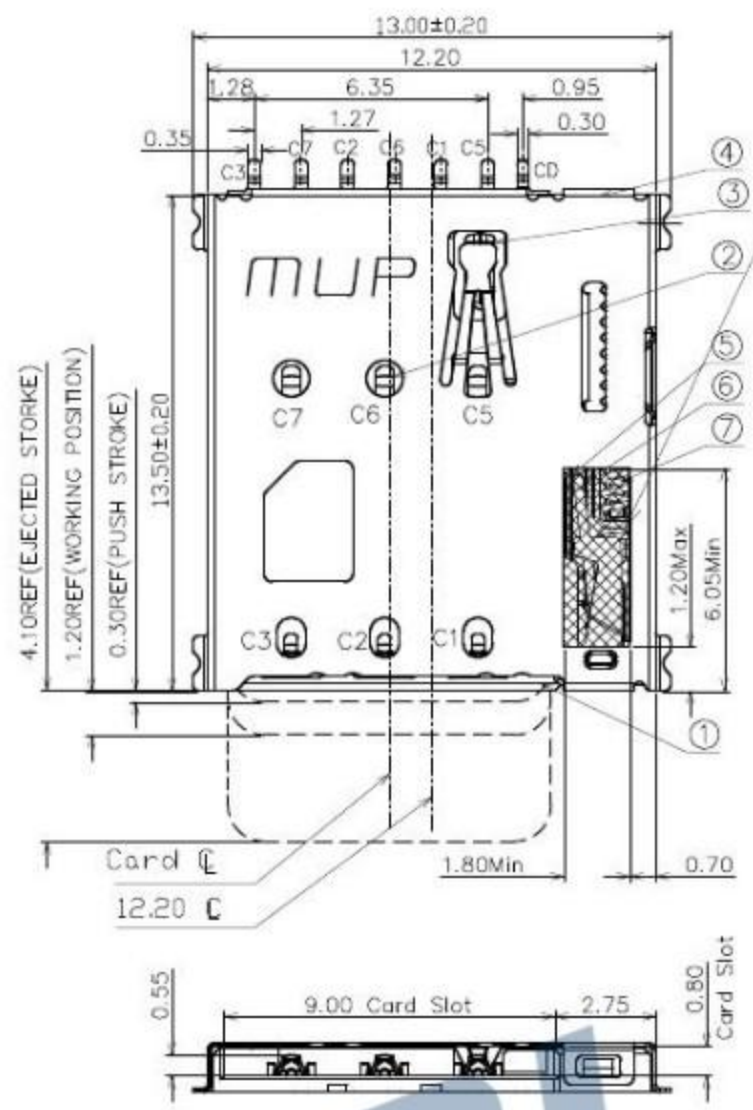
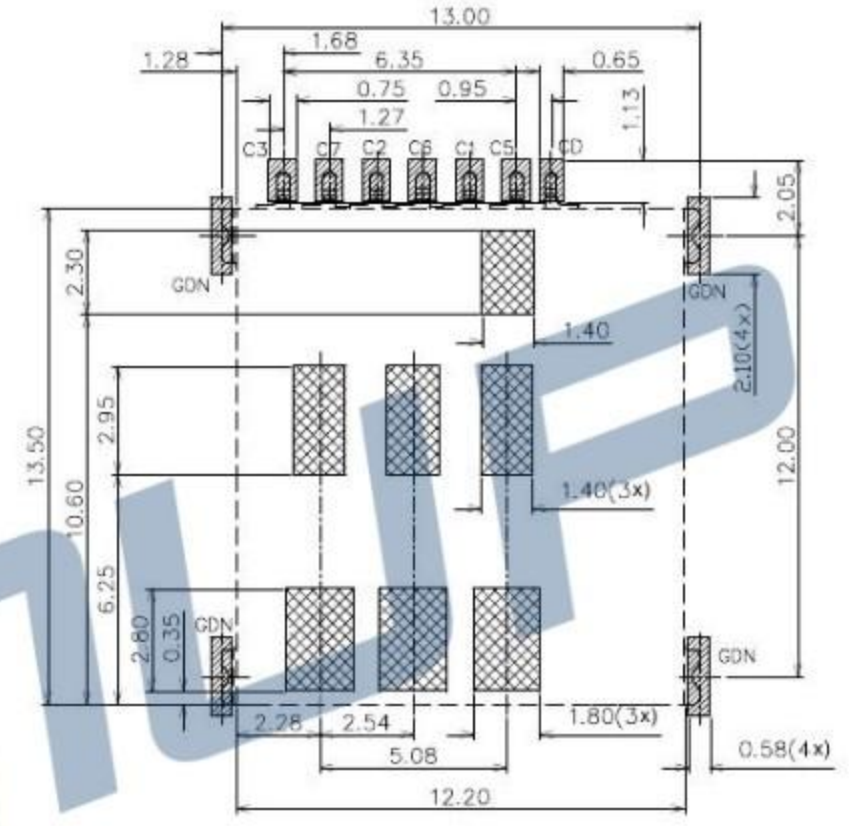


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2	Shell change				2019.11.01



OTHER COMPONENTS CANNOT TOUCH OR REST ON TOP OF THIS AREA



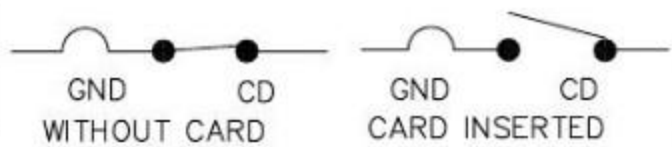
RECOMMENDED P.C.B LAYOUT COMPONENT SIDE(TOLERANCE ±0.05)

- PAD AREA
- CONNECTOR OUTLINE
- NO PATTERN AND VIA HOLE IN THIS AREA

**TECHNICAL CHARACTERISTICS**  
 1.General Characteristics  
 Dimensions:13.50LX13.0WX1.35H mm  
 Weight:Approx 0.50±0.2g  
 Durability:1,500 cycles min.  
 2.Electrical Characteristics  
 Contact resistance:50mΩ typical, 100mΩMax  
 Insulation resistance:>1000MΩ/500V DC  
 3.Solderability  
 Vaporphase:215°C, 30sec.Max  
 IR reflow:260°C,5sec.Max  
 Manual soldering:370°C.3sec.Max  
 4.Environmental Characteristics  
 Operating temperature:-40°C~+85°C  
 Operating humidity:10%~+95%RH

NAND SIM CARD	
Pin No.	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN



SWITCH OPERATION DIAGRAM

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	CD	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	Solder area:Gold plated
5	EJECT BAR	1	Hi-temp Thermoplastic	
6	CAM FOLLOER	1	Stainless Steel	
7	SPRING	1	Stainless Steel	

Unless otherwise specified, other tolerance are:  
 X ±0.35 X' ±5'  
 X.X ±0.25 X.X' ±4'  
 X.XX ±0.15 X.XX' ±3'  
 X.XXX ±0.10 X.XXX' ±2'

**MUP MUP INDUSTRIAL CO.,LTD.**  
 NAME: **Push-Push NANO-SIM Card Connector**  
 MODEL NO: **MUP-C7801-2**  
 TYPE: **Without Post / Normally Close**

PROJ.	UNIT	SCALE	DRAWN	CHECKED	APPROVAL	DWG NO.:	SHEET	REVISION
⊕	mm	1:1	Henry Ou.03.2019	Henry Ou.03.2019	Simon Ou.03.2019	DWG-MUP-C7801-2	1/1	X2



CUSTOMER DRAWING